Special Issue

Thermal Data Processing with Artificial Intelligence

Message from the Guest Editors

This Special Issue focuses on increasing the community's awareness of the importance of thermal imagery, its benefits, and challenges, as well as the need for careful analysis and design of AI solutions with specific data domains in mind. Proposals addressing various research topics are welcomed, including but not limited to:

- Thermal imaging applications in medicine, automotive, aerospace, remote sensing and GIS, wildfire and rescue, space exploration, robotics, surveillance, and other industries.
- AI design for thermal imagery including Neural Architecture Search for domain-specific tasks.
- Data translation between imaging domains.
- Thermal data generation using AI.
- Thermal infrared data analysis, including image detection, localization, and segmentation.

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Deadline for manuscript submissions

closed (20 December 2022)

Journal of Imaging

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About the Journal

Message from the Editor-in-Chief

The imaging term, specific with journal, is to be considered in its broadest sense. Image processing, image understanding and computer vision are all terms related to imaging acquisition, its processing and the extraction of relevant information from the scene to obtain the underlying knowledge. All tasks related to the above items are oriented toward specific applications in a broad range of areas and topics. The *Journal of Imaging* is conceived as an efficient vehicle in the scientific community for the communication and transmission of the progress and research results in the topics covered.

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